



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

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PRINTED CIRCUIT BOARDS

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 148 FR4 100 L36.100 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_148_FR4_100_L36.100_p18

Layers	in μ	Material	Build-Up	Assembly
Layer-1	100 μ	Copper	 (180 μ PrePreg-Type: 7628)	 A1  B
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-2	100 μ	Copper	 	
	360 μ	L-FR4		
Layer-3	100 μ	Copper	 	
	180 μ	Prepreg		
	180 μ	Prepreg	 	
Layer-99	100 μ	Copper		

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